Certificate of Registration

ENVIRONMENTAL MANAGEMENT SYSTEM - ISO 14001:2015

This is to certify that:

Samsung Electro-Mechanics Co., Ltd.
Suwon Headquarter
150, Maeyoung-ro
Yeongtong-gu
Suwon-si
Gyeonggi-do
16674
Republic of Korea

Holds Certificate No: **EMS 726540**

and operates an Environmental Management System which complies with the requirements of ISO 14001:2015 for the following scope:

The development of MLCC(MuLTI Layer Ceramic Capacitor) Power Induct, Tantalum, Common Mode Filter, Chip Resistor, Camera Module, Wifi Module, 5G Antenna, BGA(Ball Grid Arrays), FCBGA(Flip Chip Ball Grid Array). The manufacture of BGA(Ball Grid Arrays), MLCC, material, Induct, FCBGA(Flip Chip Ball Grid Array), BTP(Barium Titanate Powder).

This certificate is traceable to this company's original registration certificate No. KE 191620 dated 10/Jun/2019 and issued by Kiwa.

For and on behalf of BSI:

Chris Cheung, Head of Compliance & Risk - Asia Pacific

Original Registration Date: 2013-06-25
Latest Revision Date: 2020-04-10

Effective Date: 2020-04-10
Expiry Date: 2022-06-24

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This certificate was issued electronically and remains the property of BSI and is bound by the conditions of contract.
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Information and Contact: BSI, Kitemark Court, Davy Avenue, Knowlhill, Milton Keynes MK5 8PP. Tel: + 44 345 080 9000
BSI Assurance UK Limited, registered in England under number 7805321 at 389 Chiswick High Road, London W4 4AL, UK.
A Member of the BSI Group of Companies.

Certificate No: **EMS 726540**

Location	Registered Activities
Samsung Electro-Mechanics Co., Ltd. Suwon Headquarter 150, Maeyoung-ro Yeongtong-gu Suwon-si Gyeonggi-do 16674 Republic of Korea	The development of MLCC(MuLTI Layer Ceramic Capacitor) Power Induct, Tantalum, Common Mode Filter, Chip Resistor, Camera Module, Wifi Module, 5G Antenna, BGA(Ball Grid Arrays), FCBGA(Flip Chip Ball Grid Array). The manufacture of BGA(Ball Grid Arrays), MLCC, material, Induct, FCBGA(Flip Chip Ball Grid Array), BTP(Barium Titanate Powder).
Samsung Electro-Mechanics Co., Ltd. Busan Plant 333, Noksansaneopjung-ro Gangseo-gu Busan 46754 Republic of Korea	The manufacture of MLCC, material, Induct, FCBGA(Flip Chip Ball Grid Array).
Samsung Electro-Mechanics Co., Ltd Sejong Plant 25, Samseong-gil Yeondong-myeon Sejong-si 30067 Republic of Korea	The manufacture of BGA(Ball Grid Arrays).
Samsung Electro-Mechanics Co., Ltd Ulsan Plant 19, Yeocheon-ro 217beon-gil Nam-gu Ulsan 44714 Republic of Korea	The provision of facility management.

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